

L Number	Hits	Search Text	DB	Time stamp
-	308	(Dispersion solution slurry) and ('cmp' near5 polishing) and (silica\$2alumina silicon\$2aluminum near2 oxide silicon near2 aluminum near2 oxide)	USPAT; US-PGPUB	2004/09/27 14:26
-	124	(Dispersion solution slurry) and polishing and (silica\$2alumina silicon\$2aluminum near2 oxide)	USPAT; US-PGPUB	2004/09/27 14:22
-	50	(Dispersion solution slurry) and ('cmp' polishing) and (silica\$2alumina silicon\$2aluminum near2 oxide silicon near2 aluminum near2 oxide)	EPO; JPO; DERWENT; IBM_TDB	2004/09/27 16:50
-	4	("5891205" "5382272" "5858813" "5954997").did.	USPAT; US-PGPUB	2004/09/27 14:22